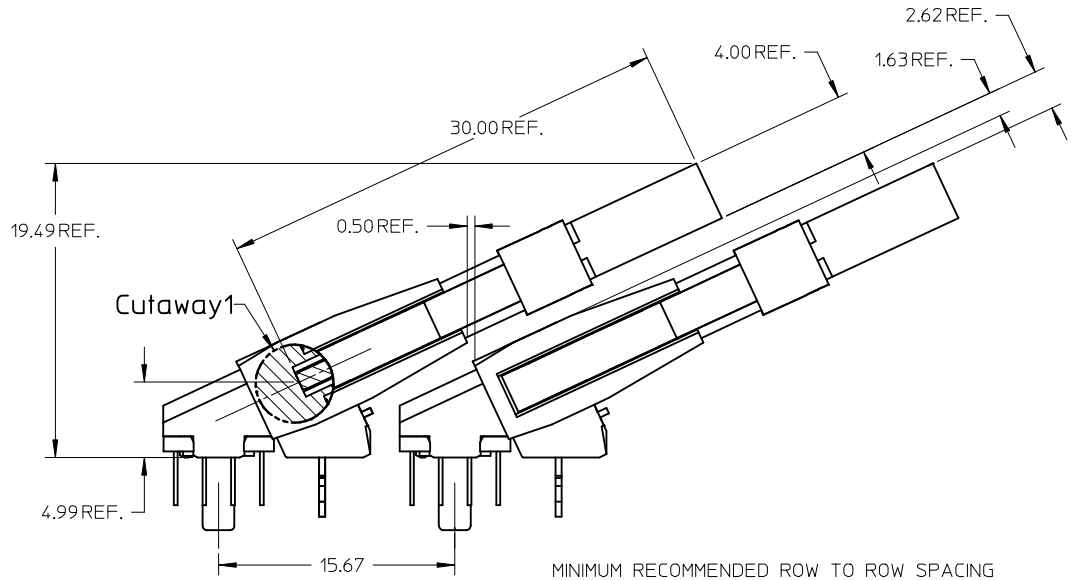


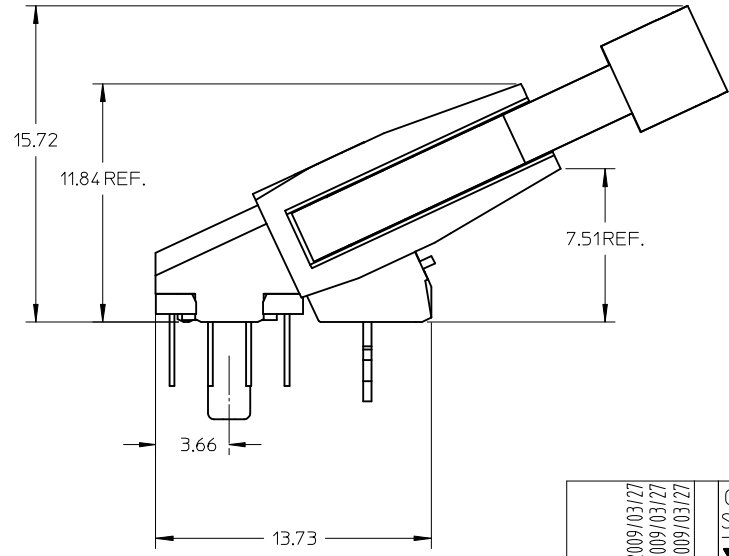
NOTES:

- MATERIALS : HOUSING AND BASEPLATE
  - LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
  - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
  - TERMINALS AND FORKLICK - COPPER ALLOY
- PLATING : CONTACT AREA - SEE TABLE IN SHEET 5  
SOLDERTAIL - SEE TABLE IN SHEET 5
- REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
- CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
- RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
- PRODUCT IS PACKED IN TRAY.
- MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
- CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

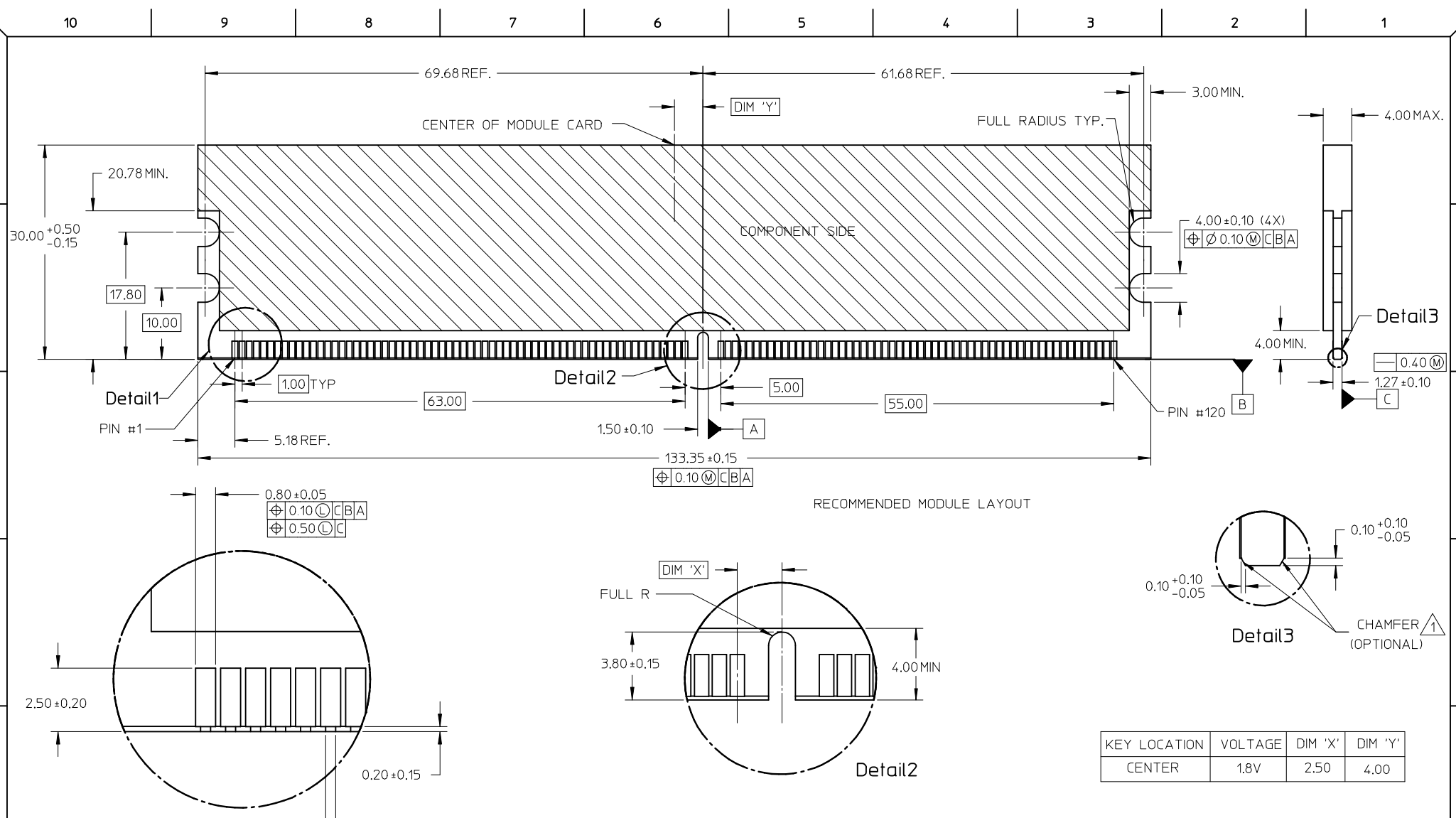
ADDED OPTION EC NO: S2009-0629 DRW: CCTEH CHKD: CGTAN APPR: SHLENI 2009/03/27 2009/03/27 2009/03/27	DESCRIPTION QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
				DRAWN BY	DATE	TITLE		
				CHECKED BY	DATE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
				MLONG	2004/03/25			
				SRRAMESH	2004/03/26			
				APPROVED BY	DATE			
				GGLEE	2004/03/26	molex MOLEX INCORPORATED		
				MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
				SEE TABLE		SD-87803-010	1 OF 5	
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				A3				



MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00MM THICK  
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH 2009/03/27 CH'KD: GGTAN 2009/03/27 APPR: SHLENI 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS, 25 DEG.			
	2 PLACES	± 0.25	± ---	SRRAMESH	2004/03/26	MOLEX INCORPORATED				
	1 PLACE	± ---	± ---	APPROVED BY	DATE	DOCUMENT NO.				
	ANGULAR ± 5 °		GGLLEE		2004/03/26	SD-87803-010				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE	SHEET NO.				
B1	REV			SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES :  
 1 MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

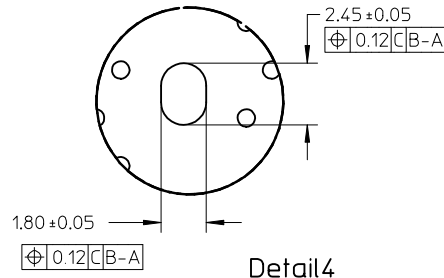
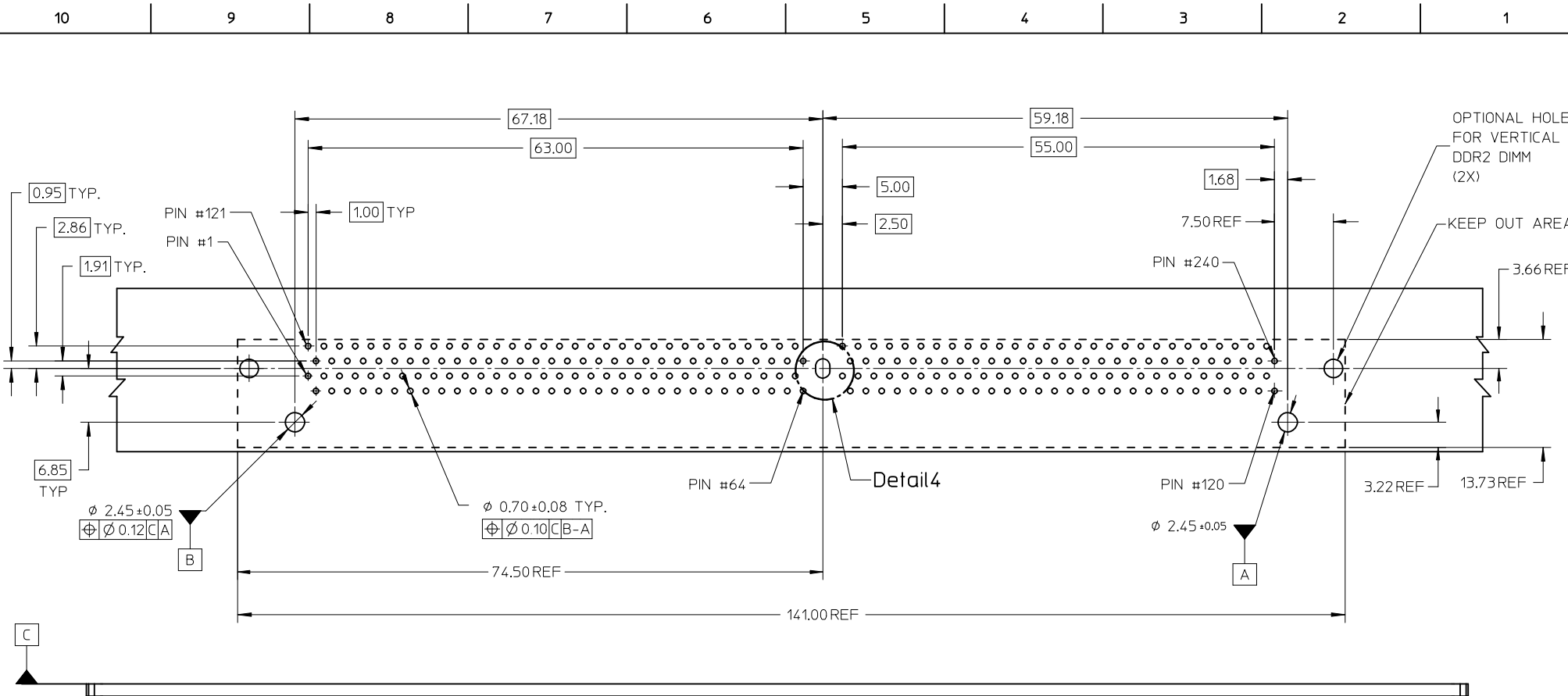
ADDED OPTION  
 EC NO: S2009-0629  
 DRW:NCCTEH  
 CHKD:CGTAN  
 APPR:SHLENI

REV	DESCRIPTION
B1	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ± ---	± ---
◻=0	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 5 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
MLONG	2004/03/25
CHECKED BY	DATE
SRRAMESH	2004/03/26
APPROVED BY	DATE
GGLEE	2004/03/26
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	☉
TITLE		
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
MOLEX INCORPORATED		SHEET NO.
DOCUMENT NO. SD-87803-010		3 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



<b>ADDED OPTION</b> EC NO: S2009-0629 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI	2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$\nabla = 0$ $\nabla \square = 0$	mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	DRAWN BY DATE		TITLE		MOLEX INCORPORATED SD-87803-010		
		ANGULAR ± 5 °	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	B1	MATERIAL NO.	SEE TABLE		MOLEX INCORPORATED DOCUMENT NO.		SHEET NO.		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	SIZE A3		SD-87803-010		4 OF 5		

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38uM/ 15u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN, TIN (MATTE) OVER 1.27uM/ 50u" MIN NICKEL	NO
87803-0022							YES
87803-0012		3.18	4.83	2.36			NO
87803-0032							YES
87803-0052		4.00	3.18	NO			
87803-0062				YES			
87803-0102		2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		NO
87803-0122							YES
87803-0112		3.18	4.83	2.36			NO
87803-0132							YES
87803-0152		4.00	3.18	NO			
87803-0162				YES			

ADDED OPTION EC NO: S2009-0629 DRWN: CCTE CH'KD: GTAN APPR: SILENI 2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla = 0$ $\triangle = 0$	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: MLONG    DATE: 2004/03/25 CHECKED BY: SRRAMESH    DATE: 2004/03/26 APPROVED BY: GGLEE    DATE: 2004/03/26	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.	
	REV		MATERIAL NO.	SEE TABLE	MOLEX INCORPORATED	
B1			SIZE A3	DOCUMENT NO. SD-87803-010		SHEET NO. 5 OF 5